

# CMSE 2026 PROGRAM BOOK



**29<sup>th</sup> Annual  
Components for Military & Space Electronics  
Conference & Exhibition**

**April 28 - April 30, 2026**  
Renaissance Hotel, LAX  
9620 Airport Blvd.  
Los Angeles, CA 90045

## CMSE 2026 Message from the Chair

On behalf of the CMSE Program Committee I would like to personally welcome everyone to the 29th annual CMSE Conference and Exhibition. Our mission is to provide a conference experience focused on high quality technical talks, keynotes, tutorials and discussions that foster maximum attendee participation/interaction and furthers our collective understanding of the technical challenges faced in our industry. We look to showcase the supplier base to the greatest extent possible and to educate the industry, especially young component engineers, to secure the future defense of our country.

This year we added a "Lunch and Learn" speaker on Wednesday to try and attract local engineers to stop by and visit the exhibits. We've also added two new tutorials on Tuesday. One focused on failure analysis and the other on next generation fan out wafer level packaging 2.3 D (FO-WLP).

Your feedback is welcome. I'd like to personally thank Brian Schieman at IMAPS for their support and all our sponsors and exhibitors for supporting CMSE. Enjoy CMSE 2026!

Pay attention, take the time to listen, ask good questions and don't hesitate to respectfully challenge each other's ideas and technical opinions.

Welcome to CMSE 2026!



Thomas Green  
CMSE Program Chair



ORGANIZED BY: TJ Green Associates

## Program Committee

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# 2026 KEYNOTE SPEAKERS



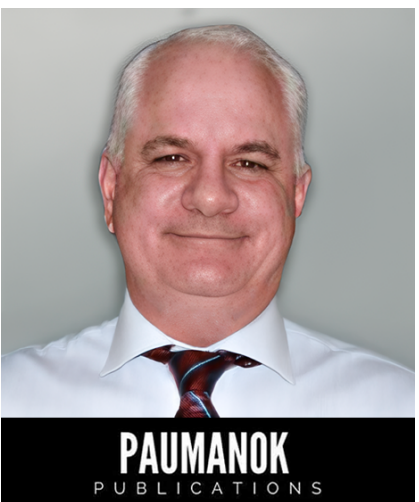
## Devanand K. Shenoy, Ph.D. Strategic Advisor to IBM Semiconductors within IBM Research

Dr. Dev Shenoy is a Strategic Advisor to IBM Semiconductors within IBM Research and formerly served as Principal Director for Microelectronics at the Office of the Under Secretary of War for Research and Engineering (OUSW(R&E)), leading efforts to equip the Warfighter with advanced semiconductor capabilities.

He founded the CHIPS Act-funded Microelectronics Commons (ME Commons) program to strengthen U.S. Lab-to-Fab prototyping, onshore manufacturing, workforce development, and intellectual property protection, ensuring access to cutting-edge microelectronics for advanced weapons systems. He also built interagency collaborations with the National Science Foundation and Department of Commerce.

Dr. Shenoy oversaw initiatives including the Trusted and Assured Microelectronics Program, the Defense Microelectronics Cross-Functional Team, and the Strategic Radiation Hardened Electronics Council, while launching power electronics projects for hypersonics, directed energy, AI, and autonomy.

Previously, he held leadership roles at USC/ISI, DARPA, the Department of Energy, and within defense industrial base policy, creating public-private partnerships and driving innovation in microelectronics and photonics for defense and commercial applications.



## Dennis M. Zogbi Founder and CEO of Paumanok Publications, Inc.

Dennis M. Zogbi is the founder and CEO of Paumanok Publications, Inc. and a globally recognized authority on passive electronic components. With 37 years of continuous research (1988–2026) and more than 260 published reports, he is a trusted expert on capacitors, resistors, inductors, circuit protection devices and their supply chains.

He founded Paumanok in 1988 while attending university in New York, beginning with a study on the global varistor market. This work expanded into a comprehensive research model analyzing the full supply chain, from raw materials to end-use markets across industries like automotive, telecommunications, defense, and renewable energy.

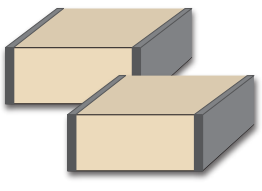
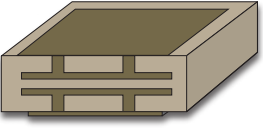
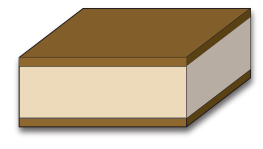
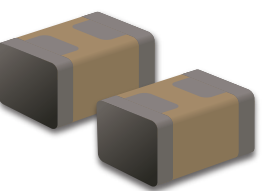
Zogbi's long-term dataset enables deep trend analysis, forecasting, and insight into industry cycles. He also developed the Passive Component Raw Material Index to track key materials and market shifts.

He is the majority owner of Passive Component Industry Magazine and a regular contributor to TTI's MarketEYE, shaping global industry insight.



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# 2026 TUTORIAL SCHEDULE

TUESDAY, APRIL 28

0700-0900	Registration and Student Breakfast Sponsored by All Tech Electronics	
<b>TUTORIAL #1</b> LOCATION: Malibu Room		
0800-1600	Advanced Microelectronic Component Engineering Principles and Practices	Instructors: Thomas J Green (TJ Green Associates) Ron Demcko (Kyocera AVX) Trevor Devaney (Hi-Rel Labs) Jerard Jose (Vishay)
<b>TUTORIAL #2</b> LOCATION: Venice Room		
0800-1200	Introduction to Electronics Failure Analysis	Instructor: Ken Turner (Hi-Rel Laboratories)
1200-1300	STUDENT LUNCH: In Renaissance IV Sponsored by All Tech Electronics (For those attending tutorial classes only)	
<b>TUTORIAL #3</b> LOCATION: Venice Room		
1300-1700	Introduction to and Advances in 2.3D Fan-Out Wafer Level Packaging (FO-WLP)	Instructor: Beth Keser (Volantis Semiconductor)
<b>TUTORIAL #4</b> LOCATION: International Ballroom		
1615-1745	Understanding Military Standards and Update on JEDEC and New Spec Initiatives	Instructors: Ben Mendoza (Promex Industries) Shri Agarwal (NASA JPL) Adam Johnson (Integra Technologies)

1800-1900 (Malibu Room)  
**STUDENT & PROFESSIONAL**  
Networking Reception

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THURSDAY, APRIL 30

0700	REGISTRATION & COFFEE	
<b>Session 2A</b>		<b>Session Chair: Jerard Jose (Vishay)</b>
0800-0845	KEYNOTE: Ultra-Low Loss and Precision Passive Components for Quantum Computing: Market Opportunities and Technology Requirements 2025-2030	Dennis Zogbi Paumanok Publications
0845-0910	Limitations in Today's Passive Electrical Components	Dr. Eric Langlois BAE Systems   FASTLABS
0910-0935	Low Inductance Bulk Capacitors	Ron Demcko Kyocera AVX
0935-1000	New High Voltage Reconstituted Mica Capacitors to Pulse or Filter in One Small SMD Package	Mickael Dubois Exxelia
1000-1030	COFFEE BREAK: Sponsored by Presidio	
1030-1050	Eliminating Wirebonds in RF Modules: A New Class of Low-ESL Capacitors	Mark Simpson UTC & Eulex (Evans Group)
1050-1110	Why Capacitors Do What They Do	David Zawacki CalRamic Technologies
1110-1130	Predicting TVA Attenuation Across Temperature Using Measurement-Based Mathematical Models	Wes Laquerre IMS
1130-1150	Wire Bonding, Laser Welding, and Ultrasonic Smart Welding for Space Applications	Mike McKeown, Ph.D. Hesse Mechatronics
1150-1210	From Spaceflight to EUV Lithography: High Reliability Outgassing and RGA Testing	Jayeshkumar Das Oneida Research Services
1210-1330	LUNCH BREAK: Sponsored by Presidio	
<b>Session 2B</b>		<b>Session Chair: Larry Harzstark (Aerospace Corp)</b>
1330-1350	IBM: Pioneering Emerging Compute	Julian Warchall IBM
1350-1410	Bridging the Reliability Chasm: Applying AI-Driven Predictive Forensics to Qualify Electronics for Military & Space Environments	Eisuke Tsuyuzaki Bayflex Solutions
1410-1430	Achieving High-Reliability Semiconductor Components Production in a Fully Outsourced Manufacturing Model	Don Larson ES Components
1430-1450	An Introduction to Laser Trimming A Measurement-Driven Process	Jim Greene Photonics Systems USA
1450-1505	COFFEE BREAK: Sponsored by Presidio	
1505-1525	Integrated Thin-Film Resistor Materials for High-Frequency Applications	John Andresakis Ohmega Ticer
1525-1545	Scaling National Security: The SCALE Program's Role in Growing the Nation's Skilled Microelectronics Workforce	Peggy E. Williams, Ph.D. NSWC Crane
1545-1605	Die Solutions for Space Constrained Hybrid Applications	Joe Beck Central Semiconductor
1605-1625	Design of Ultra Narrow-Band Amplifiers for High Sensitivity Receiver Front-Ends Using Negative Resistance Devices for ESM, ECM, ECCM, ELINT, Radar, Satellite & Telecommunication Applications	Dr. Ash (Ashok) Gorwara Gorwara & Associates International, Inc
1625-1645	A RadHard Logic Level MOSFET for Military and Space Applications	Joe Benedetto VPT Components
1645-1700	John R. Devaney Award for Best Presentation at CMSE \$1,500 Cash Prize	



A microelectronic workforce development program funded by the DoW, facilitated by NSWC Crane, and managed by Purdue University.

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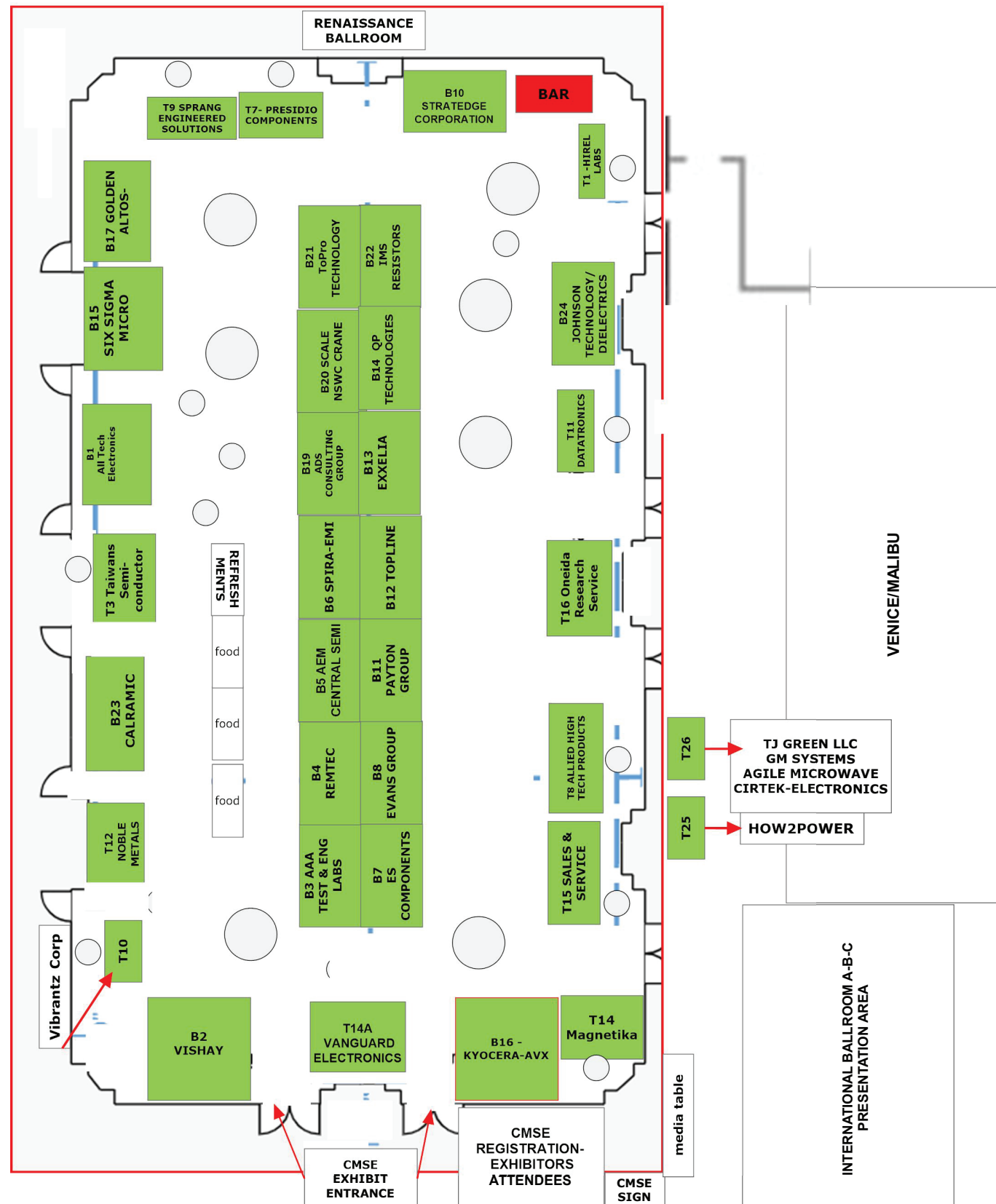


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# 2026 EXHIBIT FLOOR LAYOUT



## EXHIBITOR LISTING (ALPHABETICAL)

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B3	AAA Engineering & Test Lab
B19	ADS Consulting Group, Inc.
B5	AEM-Central Semiconductor
B1	<b>ALL TECH ELECTRONICS</b>
T8	ALLIED HIGH TECH PRODUCTS, INC
B23	CalRamic Technologies LLC
T11	DATATRONICS ROMOLAND INC
B7	ES Components
B8	Evans Group (Evans, Paktron, UTC, Eulex)
B13	EXXELIA
B17	Golden Altos Corp
T1	<b>HI-REL LABORATORIES</b>
B22	International Manufacturing Services, Inc. (IMS)
B24	Johanson Technology/Johanson Dielectrics
B16	<b>KYOCERA AVX</b>
T14	Magnetika, Inc.
T12	Noble Metal Services
T16	Oneida Research Services, Inc.
B11	Payton America
T7	<b>PRESIDIO COMPONENTS INC.</b>
B14	QP TECHNOLOGIES
B4	Remtec
T15	Sales & Service, Inc. (SSI)
B20	SCALE Program (CRANE NAVY NSWC)
B15	Six Sigma Microelectronics
T9	Spang Engineered Solutions
B6	Spira
B10	StratEdge Corp.
T3	Taiwan Semiconductor
B12	TopLine Corporation
B21	ToPro Technology Co., Ltd.
T14A	Vanguard Electronics
T10	Vibrantz Corp
B2	Vishay Intertechnology



*Thank You*

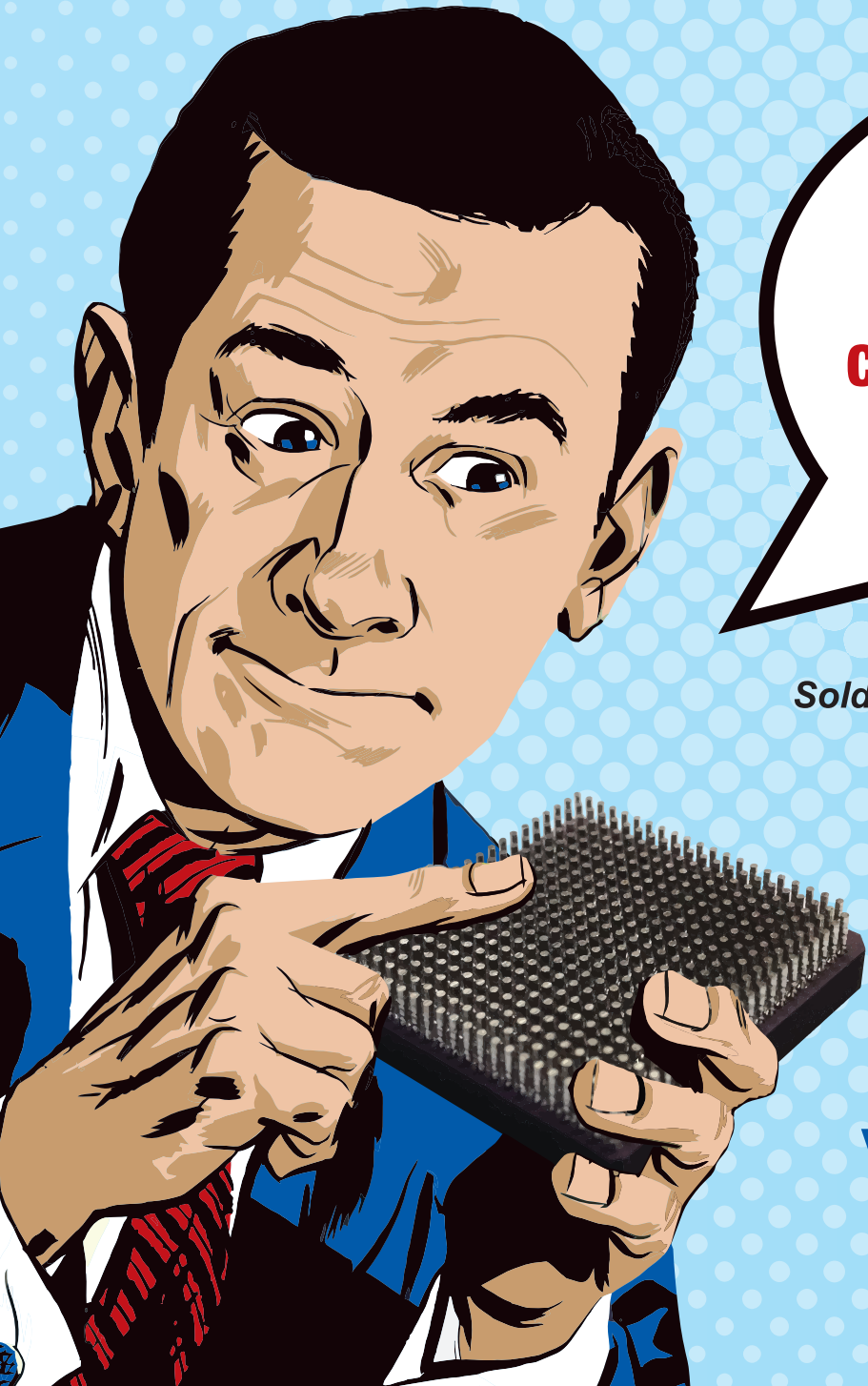
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